SN5438, SN54LS38, SN54S38 SN7438, SN74LS38, SN74S38 QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS SDLS105 – DECEMBER 1983 – REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

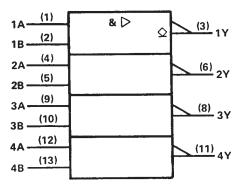
These devices contain four independent 2-input NAND buffer gates with open-collector outputs. The open-collector outputs require pull-up resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate high VOH levels.

The SN5438, SN54LS38, and SN54S38 are characterized for operation over the full military temperature range of -55° C to 125° C. The SN7438, SN74LS38, and SN74S38 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	в	Y
н	н	L
L	x	н
х	L	н

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

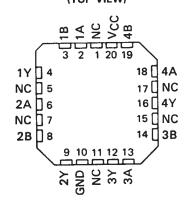
Pin numbers shown are for D, J, N, and W packages.

SN5438, SN54LS38, SN54S38 . . . J OR W PACKAGE SN7438 . . . N PACKAGE SN74LS38, SN74S38 . . . D OR N PACKAGE

(TOP VIEW)

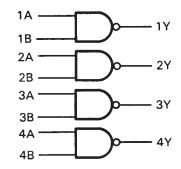
1А (1В (1	U 14 13	
ivd	3	12	
2A 🗌	4	11] 4Y
2в 🕻	5	10] ЗВ
2 Y 🗍	6	9] 3A
GND 🖸	7	8] 3Y

SN54LS38, SN54S38 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic diagram



positive logic

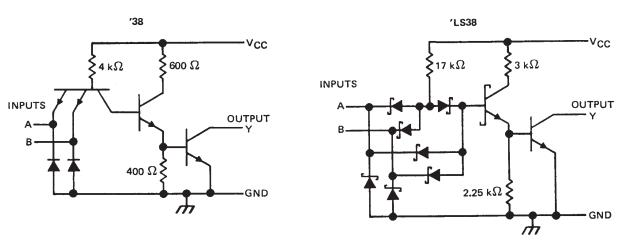
$$Y = \overline{A \cdot B}$$
 or $Y = \overline{A} + \overline{B}$

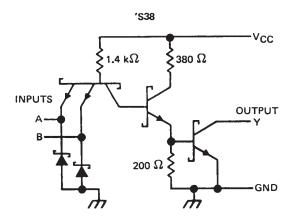
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN5438, SN54LS38, SN54S38 SN7438, SN74LS38, SN74S38 **QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS** SDLS105 – DECEMBER 1983 – REVISED MARCH 1988

schematics (each gate)





Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Supply voltage, VCC (see Note 1)		
Input voltage: '38		5.5 V
LS38		7 V
Off-state output voltage		7 V
Operating free-air temperature range:	: SN54'	5°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		5°C to 150°C
NOTE 1: Voltage values are with respect to netw	work ground terminal.	



SN5438, SN54LS38, SN54S38 SN7438, SN74LS38, SN74S38 QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS

SDLS105 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

		SN5438		SN7438			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	U.N.I
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH High-level input voltage	2			2			V
VIL Low-level input voltage			0.8			0.8	V
VOH High-level output voltage			5.5			5.5	V
IOL Low-level output current			48			48	mA
T _A Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	•	SN5438	SN7438	UNIT
PARAMETER	TEST CONDITIONS [†]	MIN TYP [‡] MAX	MIN TYP [‡] MAX	UNIT
VIK	$V_{CC} = MIN, I_i = -12 \text{ mA}$	- 1.5	- 1.5	V
	$V_{CC} = MIN, V_{IL} = 0.8 V, V_{OH} = 5.5 V$		0.25	mA
юн	$V_{CC} = MIN, V_{IL} = 0.7 V, V_{OH} = 5.5 V$	0.25		
VOL	$V_{CC} = MIN$, $V_{IH} = 2 V$, $I_{OL} = 16 mA$	0.4	0.4	V
<u> </u>	$V_{CC} = MAX, V_I = 5.5 V$	1	1	mA
<u> </u>	$V_{CC} = MAX, V_I = 2.4 V$	40	40	μA
կլ	$V_{CC} = MAX, V_1 = 0.4 V$	- 1.6	- 1.6	mA
ICCH	$V_{CC} = MAX, V_I = 0$	5 8.5	5 8.5	mA
	$V_{CC} = MAX, V_1 = 4.5 V$	34 54	34 54	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. [‡]All typical values are at V_{CC} = 5 V, T_A = 25 °C.

switching characteristics, V_{CC} = 5 V, T_A = 25° C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN TYP	MAX	UNIT
^t PLH			D = 122.0	C1 = 45 pF	14	22	ns
^t PHL	A or B	Y	R _L = 133 Ω,	CL = 45 pr	11	18	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



SN5438, SN54LS38, SN54S38 SN7438, SN74LS38, SN74S38

QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS

SDLS105 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

	S	SN54LS38			SN74LS38		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC} Supply voltage	4.5	5	5.5	4,75	5	5.25	V
VIH High-level input voltage	2			2		-	V
VIL Low-level input voltage			0.7			0.8	V
VOH High-level output voltage			5.5			5.5	V
IOL Low-level output current			12			24	mA
TA Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEAT CONDIT	uovat	5	N54LS	38	SN74LS	38	UNIT
PARAMETER		TEST CONDIT		MIN	TYP‡	MAX	MIN TYP‡	MAX	UNT
VIK	V _{CC} = MIN,	l _l = 18 mA	<u> </u>			- 1.5		- 1.5	V
ІОН	V _{CC} = MIN,	VIL = MAX,	V _{OH} = 5.5 V			0.25		0.25	mA
	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 12 mA		0.25	0.4	0.25	0.4	- v
VOL	V _{CC} = MIN,	V _{1H} = 2 V,	I _{OL} = 24 mA				0.35	0.5	
1	V _{CC} = MAX,	V _I = 7 V				0.1		0.1	mA
Чн	V _{CC} = MAX,	V ₁ = 2.7 V	· · · · · · · · · · · · · · · · · · ·			20		20	μA
կլ	V _{CC} = MAX,	V1 = 0.4 V				- 0.4		- 0.4	mA
ICCH	V _{CC} = MAX,	V ₁ = 0			0.9	2	0.9	2	mA
ICCL	V _{CC} = MAX,	V _I = 4.5 V			6	12	6	12	mA

† For conditons shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at V_{CC} = 5 V, T_A = 25^oC.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	TEST CONDITIONS			МАХ	UNIT
tPLH	A on P	V	D 407 0	C ₁ = 45 pF		20	32	ns
^t PHL	A or B	T	R _L = 667 Ω,	C[- 45 pr		18	28	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



SN5438, SN54LS38, SN54S38 SN7438, SN74LS38, SN74S38 QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS SDLS105 – DECEMBER 1983 – REVISED MARCH 1988

recommended operating conditions

		S	SN54S38		SN74S38			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC} Sup	ply voltage	4.5	5	5.5	4.75	5	5.25	V
	h-level input voltage	2			2			V
	v-level input voltage			0.8			0.8	V
	h-level output voltage			5.5			5.5	V
	v-level output current			60			60	mA
	erating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

·····	·	SN54S38	SN74S38	UNIT
PARAMETER	TEST CONDITIONS [†]	MIN TYP [‡] MAX	MIN TYP [‡] MAX	UNIT
VIK	$V_{CC} = MIN$, $I_{I} = -18 \text{ mA}$	- 1.2	- 1.2	V
	$V_{CC} = MIN, V_{IL} = 0.8 V, V_{OH} = 5.5 V$		0.25	mA
юн	$V_{CC} = MIN, V_{IL} = 0.7 V, V_{OH} = 5.5 V$	0.25		
VOL	$V_{CC} = MIN$, $V_{IH} = 2 V$, $I_{OL} = 60 mA$	0.5	0.5	V
<u> </u>	$V_{CC} = MAX$, $V_I = 5.5 V$	1	1	mA
л лн	$V_{CC} = MAX, V_I = 2.4 V$	0.1	0.1	mA
<u></u>	$V_{CC} = MAX, V_{I} = 0.5 V$	-4	- 4	mA
ІССН	$V_{CC} = MAX, V_1 = 0$	20 36	20 36	mA
	$V_{CC} = MAX, V_{I} = 4.5 V$	46 80	46 80	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. [‡]All typical values are at V_{CC} = 5 V, T_A = 25 °C.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	IDITIONS	MIN	түр	MAX	UNIT
^t PLH			$P_{1} = 02.0$	CL = 50 pF		6.5	10	ns
tPHL	1 D		R _L = 93 Ω,	0L 00 p.		6.5	10	ns
tPLH	A or B		R _L = 93 Ω,	C1 = 150 pF		9		ns
^t PHL			NL = 55 12,			8.5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.





9-Oct-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/00303BCA	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00303BCA	Samples
JM38510/30203B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30203B2A	Samples
JM38510/30203B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30203B2A	Samples
JM38510/30203BCA	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30203BCA	Samples
JM38510/30203BCA	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30203BCA	Samples
JM38510/30203BDA	ACTIVE	CFP	W	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30203BDA	Samples
JM38510/30203BDA	ACTIVE	CFP	W	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30203BDA	Samples
M38510/00303BCA	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00303BCA	Samples
M38510/00303BCA	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	N / A for Pkg Type -55 to 125		Samples
M38510/30203B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	N / A for Pkg Type -55 to 125		Samples
M38510/30203B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30203B2A	Samples
M38510/30203BCA	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30203BCA	Samples
M38510/30203BCA	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30203BCA	Samples
M38510/30203BDA	ACTIVE	CFP	W	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30203BDA	Samples
M38510/30203BDA	ACTIVE	CFP	W	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30203BDA	Samples
SN5438J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SN5438J	Samples
SN5438J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SN5438J	Samples



PACKAGE OPTION ADDENDUM

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samp
SN54LS38J	ACTIVE	CDIP	J	14	1	TBD	SNPB	SNPB N / A for Pkg Type		SN54LS38J	Samp
SN54LS38J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SN54LS38J	Samp
SN54S38J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SN54S38J	Samp
SN54S38J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SN54S38J	Samp
SN7438D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	7438	Samp
SN7438D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	7438	Samj
SN7438DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM 0 to 70		7438	Samj
SN7438DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	7438	Sam
SN7438DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	7438	Sam
SN7438DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	7438	Sam
SN7438N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN7438N	Sam
SN7438N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN7438N	Sam
SN7438NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN7438	Sam
SN7438NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN7438	Sam
SN74LS38D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS38	Sam
SN74LS38D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS38	Sam
SN74LS38DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		LS38	Sam
SN74LS38DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM		LS38	Sam



PACKAGE OPTION ADDENDUM

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Sampl
SN74LS38DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS38	Samp
SN74LS38DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS38	Samp
SN74LS38DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS38	Samp
SN74LS38DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS38	Samp
SN74LS38DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS38	Samp
SN74LS38DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM 0 to 70		LS38	Samp
SN74LS38N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type 0 to 70		SN74LS38N	Samp
SN74LS38N	ACTIVE	PDIP	Ν	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type 0 to 70		SN74LS38N	Samp
SN74LS38NE4	ACTIVE	PDIP	Ν	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS38N	Samj
SN74LS38NE4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type 0 to 70		SN74LS38N	Samp
SN74LS38NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS38	Samp
SN74LS38NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS38	Samj
SN74S38D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM 0 to 70		S38	Samj
SN74S38D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM 0 to 70		S38	Samj
SN74S38DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM 0 to 70		S38	Sam
SN74S38DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM 0 to 70		S38	Sam
SN74S38N	ACTIVE	PDIP	Ν	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74S38N	Sam



PACKAGE OPTION ADDENDUM

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samp
SN74S38N	ACTIVE	PDIP	Ν	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74S38N	Samp
SN74S38NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	74S38	Samp
SN74S38NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	74S38	Samp
SNJ5438J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SNJ5438J	Samp
SNJ5438J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SNJ5438J	Samp
SNJ5438W	ACTIVE	CFP	W	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SNJ5438W	Samp
SNJ5438W	ACTIVE	CFP	W	14	1	TBD	SNPB	N / A for Pkg Type -55 to 125		SNJ5438W	Sam
SNJ54LS38FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 38FK	Samj
SNJ54LS38FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 38FK	Sam
SNJ54LS38J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS38J	Sam
SNJ54LS38J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type -55 to 125		SNJ54LS38J	Sam
SNJ54LS38W	ACTIVE	CFP	W	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS38W	Sam
SNJ54LS38W	ACTIVE	CFP	W	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS38W	Sam
SNJ54S38FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 38FK	Sam
SNJ54S38FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 38FK	Sam
SNJ54S38J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S38J	Sam
SNJ54S38J	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S38J	Sam
SNJ54S38W	ACTIVE	CFP	W	14	1	TBD	SNPB	N / A for Pkg Type -55 to 12		SNJ54S38W	Sam
SNJ54S38W	ACTIVE	CFP	W	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S38W	Sam



www.ti.com

9-Oct-2020

⁽¹⁾ The marketing status values are defined as follows:
 ACTIVE: Product device recommended for new designs.
 LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
 NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
 PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
 OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption. **Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN5438, SN54LS38, SN54S38, SN74J8, SN74LS38, SN74S38 :

• Catalog: SN7438, SN74LS38, SN74S38

• Military: SN5438, SN54LS38, SN54S38

NOTE: Qualified Version Definitions:



www.ti.com

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN7438DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN7438NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS38DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74S38DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74S38NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

20-Dec-2018



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN7438DR	SOIC	D	14	2500	367.0	367.0	38.0
SN7438NSR	SO	NS	14	2000	367.0	367.0	38.0
SN74LS38DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74S38DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74S38NSR	SO	NS	14	2000	367.0	367.0	38.0

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14



GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2020, Texas Instruments Incorporated